



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-03-24
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Floriana San Biagio	<b>Representative Title</b>	AMS Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	DD6R*1874AR6	A	BO2A	2015-03-24
Amount	UoM	Unit type	ST ECOPACK Grade	
54.82	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	5,4,4,0.9	14	gull wing	
Comment	TSSOP 14 BODY 4.4 PITCH 0.65; MD valid for TSV324IPT and TS1874IPT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	DD6R*1874AR6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	3.007	mg	supplier	die	Silicon (Si)	7440-21-3		2.957	mg	983372	53940
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.01	mg	3326	182
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	1330	73
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.008	mg	2660	146
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.028	mg	9312	511
Leadframe	Copper & its alloys	23.883	mg	supplier	alloy	Copper (Cu)	7440-50-8		22.955	mg	961144	418734
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		0.716	mg	29979	13061
Leadframe				supplier	alloy	Magnesium (Mg)	7439-95-4		0.036	mg	1507	657
Leadframe				supplier	alloy	Silicon (Si)	7440-21-3		0.155	mg	6490	2827
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.018	mg	754	328
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	42	18
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	42	18
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	42	18
Die attach	Other Organic Materials	0.949	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.864	mg	910432	15761
Die attach				supplier	glue or tape	acrylate	Proprietary		0.047	mg	49526	857
Die attach				supplier	glue or tape	Methacrylate	Proprietary		0.038	mg	40042	693
Bonding wire	Other inorganic materials	0.127	mg	supplier	wire	Copper (Cu)	7440-50-8		0.127	mg	1000000	2317
encapsulation	Other Organic Materials	26.854	mg	supplier	mold compound	Silica, vitreous	60676-86-0		23.551	mg	877002	429606
encapsulation				supplier	mold compound	Epoxy resin A	EC 413-900-7		1.074	mg	39994	19591
encapsulation				supplier	mold compound	Epoxy resin B	29690-82-2		1.074	mg	39994	19591
encapsulation				supplier	mold compound	phenol resin	Proprietary		0.806	mg	30014	14703
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.08	mg	2979	1459
encapsulation				supplier	mold compound	additive	Proprietary		0.269	mg	10017	4907